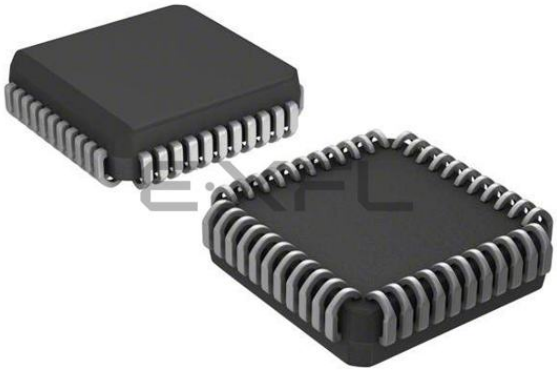

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LVD, POR, PWM, WDT
Number of I/O	34
Program Memory Size	16KB (8K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	768 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.59x16.59)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18lf442-i-l

TABLE 1-3: PIC18F4X2 PINOUT I/O DESCRIPTIONS (CONTINUED)

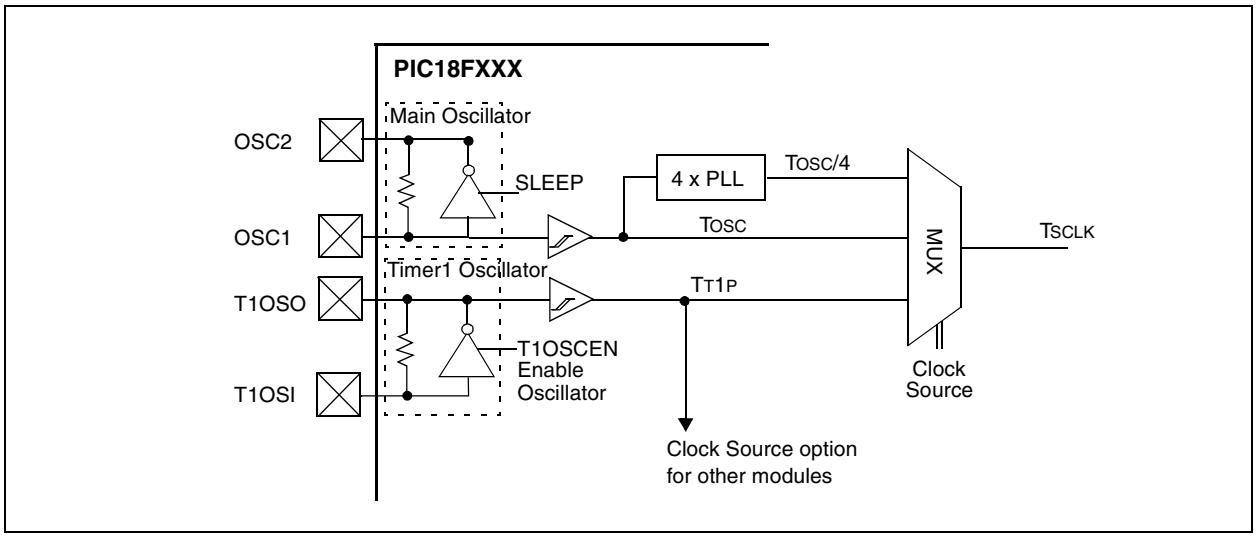
Pin Name	Pin Number			Pin Type	Buffer Type	Description
	DIP	PLCC	TQFP			
						PORTD is a bi-directional I/O port, or a Parallel Slave Port (PSP) for interfacing to a microprocessor port. These pins have TTL input buffers when PSP module is enabled.
RD0/PSP0	19	21	38	I/O	ST TTL	Digital I/O. Parallel Slave Port Data.
RD1/PSP1	20	22	39	I/O	ST TTL	Digital I/O. Parallel Slave Port Data.
RD2/PSP2	21	23	40	I/O	ST TTL	Digital I/O. Parallel Slave Port Data.
RD3/PSP3	22	24	41	I/O	ST TTL	Digital I/O. Parallel Slave Port Data.
RD4/PSP4	27	30	2	I/O	ST TTL	Digital I/O. Parallel Slave Port Data.
RD5/PSP5	28	31	3	I/O	ST TTL	Digital I/O. Parallel Slave Port Data.
RD6/PSP6	29	32	4	I/O	ST TTL	Digital I/O. Parallel Slave Port Data.
RD7/PSP7	30	33	5	I/O	ST TTL	Digital I/O. Parallel Slave Port Data.
						PORTE is a bi-directional I/O port.
RE0/$\overline{RD}$/AN5 RE0 $\overline{RD}$ AN5	8	9	25	I/O 	 ST TTL Analog	 Digital I/O. Read control for parallel slave port (see also $\overline{WR}$ and $\overline{CS}$ pins). Analog input 5.
RE1/$\overline{WR}$/AN6 RE1 $\overline{WR}$ AN6	9	10	26	I/O 	 ST TTL Analog	 Digital I/O. Write control for parallel slave port (see $\overline{CS}$ and $\overline{RD}$ pins). Analog input 6.
RE2/$\overline{CS}$/AN7 RE2 $\overline{CS}$ AN7	10	11	27	I/O 	 ST TTL Analog	 Digital I/O. Chip Select control for parallel slave port (see related $\overline{RD}$ and $\overline{WR}$). Analog input 7.
VSS	12, 31	13, 34	6, 29	P	—	Ground reference for logic and I/O pins.
VDD	11, 32	12, 35	7, 28	P	—	Positive supply for logic and I/O pins.

Legend: TTL = TTL compatible input
CMOS = CMOS compatible input or output
ST = Schmitt Trigger input with CMOS levels
I = Input
O = Output
P = Power
OD = Open Drain (no P diode to VDD)

2.6 Oscillator Switching Feature

The PIC18FXX2 devices include a feature that allows the system clock source to be switched from the main oscillator to an alternate low frequency clock source. For the PIC18FXX2 devices, this alternate clock source is the Timer1 oscillator. If a low frequency crystal (32 kHz, for example) has been attached to the Timer1 oscillator pins and the Timer1 oscillator has been enabled, the device can switch to a Low Power Execution mode. Figure 2-7 shows a block diagram of the system clock sources. The clock switching feature is enabled by programming the Oscillator Switching Enable (OSCSEN) bit in Configuration Register1H to a '0'. Clock switching is disabled in an erased device. See Section 11.0 for further details of the Timer1 oscillator. See Section 19.0 for Configuration Register details.

FIGURE 2-7: DEVICE CLOCK SOURCES

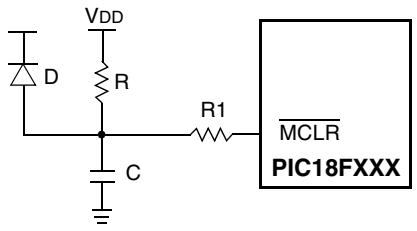


3.1 Power-On Reset (POR)

A Power-on Reset pulse is generated on-chip when VDD rise is detected. To take advantage of the POR circuitry, just tie the MCLR pin directly (or through a resistor) to VDD. This will eliminate external RC components usually needed to create a Power-on Reset delay. A minimum rise rate for VDD is specified (parameter D004). For a slow rise time, see Figure 3-2.

When the device starts normal operation (i.e., exits the RESET condition), device operating parameters (voltage, frequency, temperature, etc.) must be met to ensure operation. If these conditions are not met, the device must be held in RESET until the operating conditions are met.

FIGURE 3-2: EXTERNAL POWER-ON RESET CIRCUIT (FOR SLOW VDD POWER-UP)



Note 1: External Power-on Reset circuit is required only if the VDD power-up slope is too slow. The diode D helps discharge the capacitor quickly when VDD powers down.

2: R < 40 kΩ is recommended to make sure that the voltage drop across R does not violate the device's electrical specification.

3: R1 = 100Ω to 1 kΩ will limit any current flowing into MCLR from external capacitor C, in the event of MCLR/VPP pin breakdown due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS).

3.2 Power-up Timer (PWRT)

The Power-up Timer provides a fixed nominal time-out (parameter 33) only on power-up from the POR. The Power-up Timer operates on an internal RC oscillator. The chip is kept in RESET as long as the PWRT is active. The PWRT's time delay allows VDD to rise to an acceptable level. A configuration bit is provided to enable/disable the PWRT.

The power-up time delay will vary from chip-to-chip due to VDD, temperature and process variation. See DC parameter D033 for details.

3.3 Oscillator Start-up Timer (OST)

The Oscillator Start-up Timer (OST) provides a 1024 oscillator cycle (from OSC1 input) delay after the PWRT delay is over (parameter 32). This ensures that the crystal oscillator or resonator has started and stabilized.

The OST time-out is invoked only for XT, LP and HS modes and only on Power-on Reset or wake-up from SLEEP.

3.4 PLL Lock Time-out

With the PLL enabled, the time-out sequence following a Power-on Reset is different from other Oscillator modes. A portion of the Power-up Timer is used to provide a fixed time-out that is sufficient for the PLL to lock to the main oscillator frequency. This PLL lock time-out (TPLL) is typically 2 ms and follows the oscillator start-up time-out (OST).

3.5 Brown-out Reset (BOR)

A configuration bit, BOREN, can disable (if clear/programmed), or enable (if set) the Brown-out Reset circuitry. If VDD falls below parameter D005 for greater than parameter 35, the brown-out situation will reset the chip. A RESET may not occur if VDD falls below parameter D005 for less than parameter 35. The chip will remain in Brown-out Reset until VDD rises above BVDD. If the Power-up Timer is enabled, it will be invoked after VDD rises above BVDD; it then will keep the chip in RESET for an additional time delay (parameter 33). If VDD drops below BVDD while the Power-up Timer is running, the chip will go back into a Brown-out Reset and the Power-up Timer will be initialized. Once VDD rises above BVDD, the Power-up Timer will execute the additional time delay.

3.6 Time-out Sequence

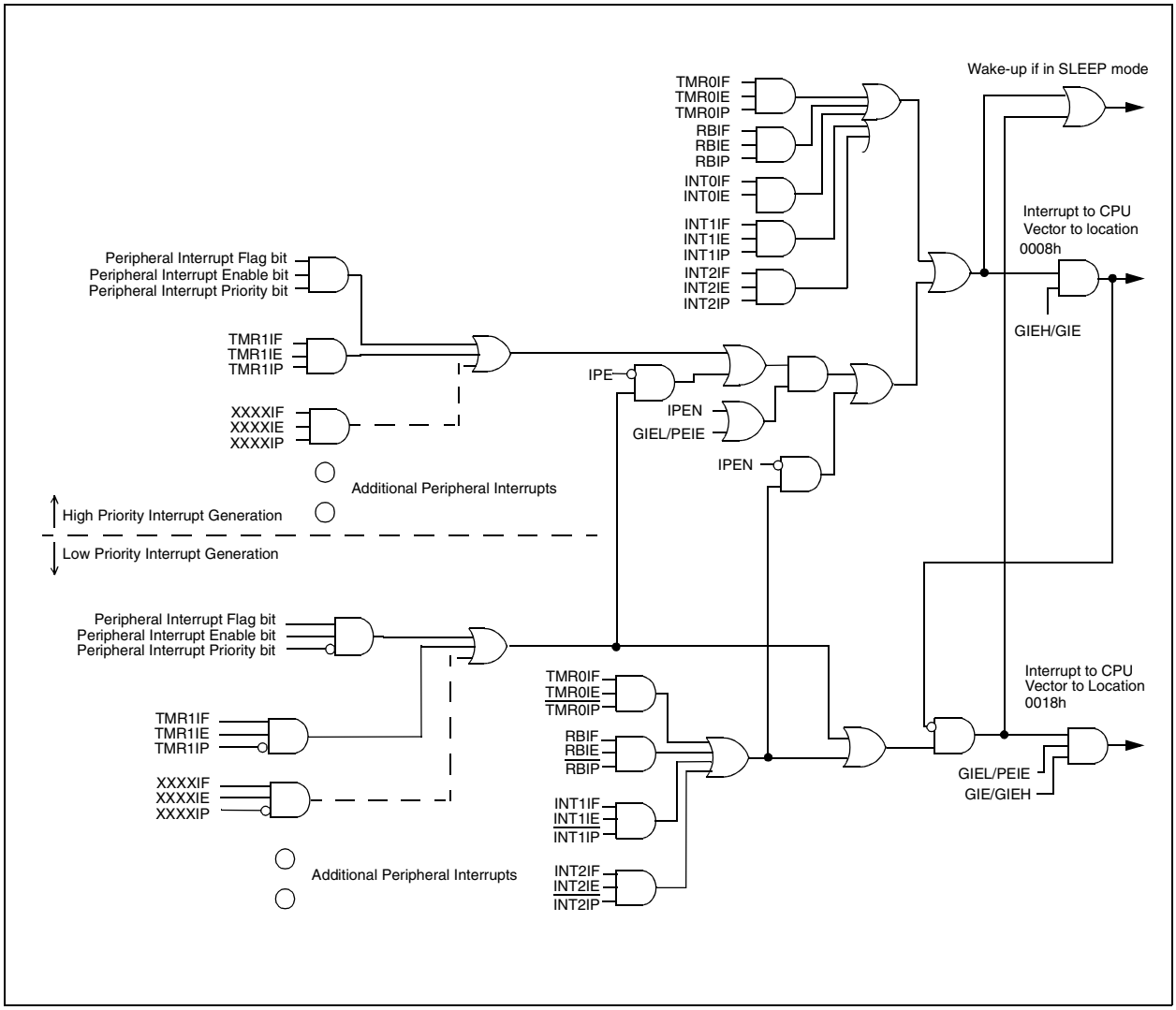
On power-up, the time-out sequence is as follows: First, PWRT time-out is invoked after the POR time delay has expired. Then, OST is activated. The total time-out will vary based on oscillator configuration and the status of the PWRT. For example, in RC mode with the PWRT disabled, there will be no time-out at all. Figure 3-3, Figure 3-4, Figure 3-5, Figure 3-6 and Figure 3-7 depict time-out sequences on power-up.

Since the time-outs occur from the POR pulse, if MCLR is kept low long enough, the time-outs will expire. Bringing MCLR high will begin execution immediately (Figure 3-5). This is useful for testing purposes or to synchronize more than one PIC18FXXX device operating in parallel.

Table 3-2 shows the RESET conditions for some Special Function Registers, while Table 3-3 shows the RESET conditions for all the registers.

NOTES:

FIGURE 8-1: INTERRUPT LOGIC



REGISTER 8-3: INTCON3 REGISTER

R/W-1	R/W-1	U-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0
INT2IP	INT1IP	—	INT2IE	INT1IE	—	INT2IF	INT1IF
bit 7							bit 0

bit 7 **INT2IP:** INT2 External Interrupt Priority bit
1 = High priority
0 = Low priority

bit 6 **INT1IP:** INT1 External Interrupt Priority bit
1 = High priority
0 = Low priority

bit 5 **Unimplemented:** Read as '0'

bit 4 **INT2IE:** INT2 External Interrupt Enable bit
1 = Enables the INT2 external interrupt
0 = Disables the INT2 external interrupt

bit 3 **INT1IE:** INT1 External Interrupt Enable bit
1 = Enables the INT1 external interrupt
0 = Disables the INT1 external interrupt

bit 2 **Unimplemented:** Read as '0'

bit 1 **INT2IF:** INT2 External Interrupt Flag bit
1 = The INT2 external interrupt occurred (must be cleared in software)
0 = The INT2 external interrupt did not occur

bit 0 **INT1IF:** INT1 External Interrupt Flag bit
1 = The INT1 external interrupt occurred (must be cleared in software)
0 = The INT1 external interrupt did not occur

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
- n = Value at POR	’1’ = Bit is set	’0’ = Bit is cleared	x = Bit is unknown

Note: Interrupt flag bits are set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the global enable bit. User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt. This feature allows for software polling.

TABLE 9-5: PORTC FUNCTIONS

Name	Bit#	Buffer Type	Function
RC0/T1OSO/T1CKI	bit0	ST	Input/output port pin or Timer1 oscillator output/Timer1 clock input.
RC1/T1OSI/CCP2	bit1	ST	Input/output port pin, Timer1 oscillator input, or Capture2 input/ Compare2 output/PWM output when CCP2MX configuration bit is set.
RC2/CCP1	bit2	ST	Input/output port pin or Capture1 input/Compare1 output/PWM1 output.
RC3/SCK/SCL	bit3	ST	RC3 can also be the synchronous serial clock for both SPI and I^2C modes.
RC4/SDI/SDA	bit4	ST	RC4 can also be the SPI Data In (SPI mode) or Data I/O (I^2C mode).
RC5/SDO	bit5	ST	Input/output port pin or Synchronous Serial Port data output.
RC6/TX/CK	bit6	ST	Input/output port pin, Addressable USART Asynchronous Transmit, or Addressable USART Synchronous Clock.
RC7/RX/DT	bit7	ST	Input/output port pin, Addressable USART Asynchronous Receive, or Addressable USART Synchronous Data.

Legend: ST = Schmitt Trigger input

TABLE 9-6: SUMMARY OF REGISTERS ASSOCIATED WITH PORTC

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on All Other RESETS
PORTC	RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0	xxxx xxxx	uuuu uuuu
LATC	LATC Data Output Register								xxxx xxxx	uuuu uuuu
TRISC	PORTC Data Direction Register								1111 1111	1111 1111

Legend: x = unknown, u = unchanged

TABLE 9-9: PORTE FUNCTIONS

Name	Bit#	Buffer Type	Function
RE0/$\overline{RD}$/AN5	bit0	ST/TTL(1)	Input/output port pin or read control input in Parallel Slave Port mode or analog input: $\overline{RD}$ 1 = Not a read operation 0 = Read operation. Reads PORTD register (if chip selected).
RE1/$\overline{WR}$/AN6	bit1	ST/TTL(1)	Input/output port pin or write control input in Parallel Slave Port mode or analog input: $\overline{WR}$ 1 = Not a write operation 0 = Write operation. Writes PORTD register (if chip selected).
RE2/$\overline{CS}$/AN7	bit2	ST/TTL(1)	Input/output port pin or chip select control input in Parallel Slave Port mode or analog input: $\overline{CS}$ 1 = Device is not selected 0 = Device is selected

Legend: ST = Schmitt Trigger input, TTL = TTL input

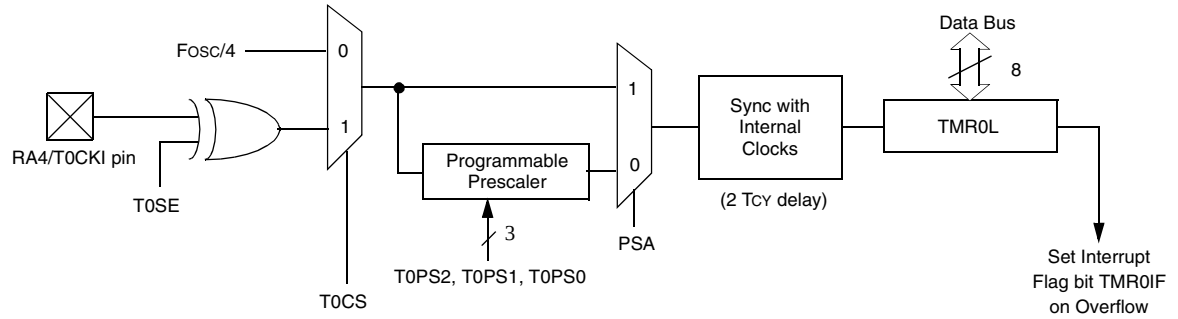
Note 1: Input buffers are Schmitt Triggers when in I/O mode and TTL buffers when in Parallel Slave Port mode.

TABLE 9-10: SUMMARY OF REGISTERS ASSOCIATED WITH PORTE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on All Other RESETS
PORTE	—	—	—	—	—	RE2	RE1	RE0	---- -000	---- -000
LATE	—	—	—	—	—	LATE Data Output Register			---- -xxx	---- -uuu
TRISE	IBF	OBF	IBOV	PSPMODE	—	PORTE Data Direction bits			0000 -111	0000 -111
ADCON1	ADFM	ADCS2	—	—	PCFG3	PCFG2	PCFG1	PCFG0	00-- 0000	00-- 0000

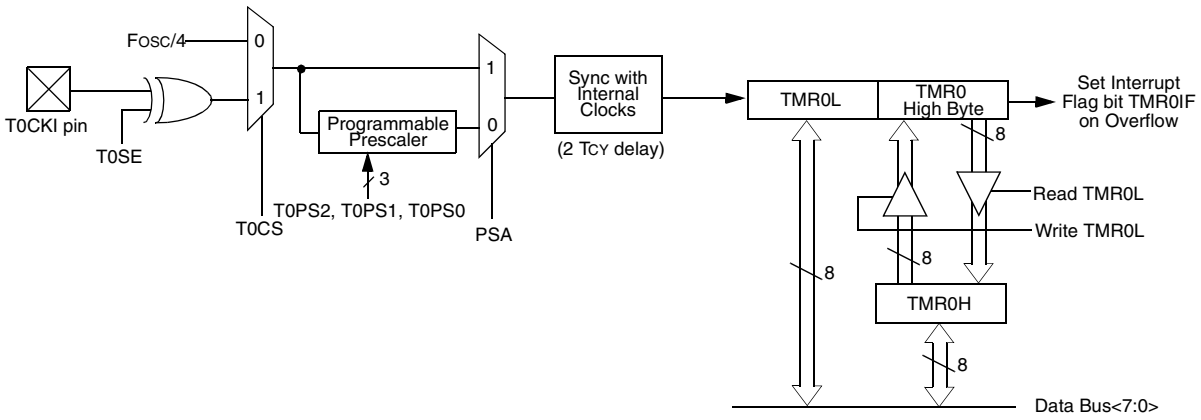
Legend: x = unknown, u = unchanged, - = unimplemented, read as '0'. Shaded cells are not used by PORTE.

FIGURE 10-1: TIMER0 BLOCK DIAGRAM IN 8-BIT MODE



Note: Upon RESET, Timer0 is enabled in 8-bit mode with clock input from T0CKI max. prescale.

FIGURE 10-2: TIMER0 BLOCK DIAGRAM IN 16-BIT MODE



Note: Upon RESET, Timer0 is enabled in 8-bit mode with clock input from T0CKI max. prescale.

NOTES:

13.2 Timer1 Oscillator

The Timer1 oscillator may be used as the clock source for Timer3. The Timer1 oscillator is enabled by setting the T1OSCEN (T1CON<3>) bit. The oscillator is a low power oscillator rated up to 200 KHz. See Section 11.0 for further details.

13.3 Timer3 Interrupt

The TMR3 Register pair (TMR3H:TMR3L) increments from 0000h to FFFFh and rolls over to 0000h. The TMR3 Interrupt, if enabled, is generated on overflow, which is latched in interrupt flag bit, TMR3IF (PIR2<1>). This interrupt can be enabled/disabled by setting/clearing TMR3 interrupt enable bit, TMR3IE (PIE2<1>).

13.4 Resetting Timer3 Using a CCP Trigger Output

If the CCP module is configured in Compare mode to generate a “special event trigger” (CCP1M3:CCP1M0 = 1011), this signal will reset Timer3.

Note:	The special event triggers from the CCP module will not set interrupt flag bit, TMR3IF (PIR1<0>).

Timer3 must be configured for either Timer or Synchronized Counter mode to take advantage of this feature. If Timer3 is running in Asynchronous Counter mode, this RESET operation may not work. In the event that a write to Timer3 coincides with a special event trigger from CCP1, the write will take precedence. In this mode of operation, the CCPR1H:CCPR1L registers pair effectively becomes the period register for Timer3.

TABLE 13-1: REGISTERS ASSOCIATED WITH TIMER3 AS A TIMER/COUNTER

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on All Other RESETS
INTCON	GIE/ GIEH	PEIE/ GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	0000 000x	0000 000u
PIR2	—	—	—	EEIF	BCLIF	LVDIF	TMR3IF	CCP2IF	---0 0000	---0 0000
PIE2	—	—	—	EEIE	BCLIE	LVDIE	TMR3IE	CCP2IE	---0 0000	---0 0000
IPR2	—	—	—	EEIP	BCLIP	LVDIP	TMR3IP	CCP2IP	---1 1111	---1 1111
TMR3L	Holding Register for the Least Significant Byte of the 16-bit TMR3 Register								xxxx xxxx	uuuu uuuu
TMR3H	Holding Register for the Most Significant Byte of the 16-bit TMR3 Register								xxxx xxxx	uuuu uuuu
T1CON	RD16	—	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{\text{T1SYNC}}$	TMR1CS	TMR1ON	0-00 0000	u-uu uuuu
T3CON	RD16	T3CCP2	T3CKPS1	T3CKPS0	T3CCP1	$\overline{\text{T3SYNC}}$	TMR3CS	TMR3ON	0000 0000	uuuu uuuu

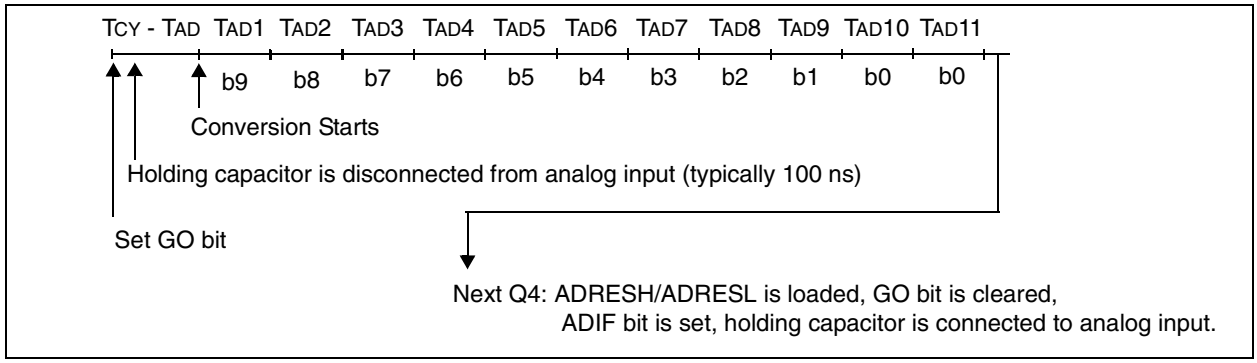
Legend: x = unknown, u = unchanged, - = unimplemented, read as '0'. Shaded cells are not used by the Timer1 module.

17.4 A/D Conversions

Figure 17-3 shows the operation of the A/D converter after the GO bit has been set. Clearing the GO/DONE bit during a conversion will abort the current conversion. The A/D result register pair will NOT be updated with the partially completed A/D conversion sample. That is, the ADRESH:ADRESL registers will continue to contain the value of the last completed conversion (or the last value written to the ADRESH:ADRESL registers). After the A/D conversion is aborted, a 2 TAD wait is required before the next acquisition is started. After this 2 TAD wait, acquisition on the selected channel is automatically started. The GO/DONE bit can then be set to start the conversion.

Note:	The GO/DONE bit should **NOT** be set in the same instruction that turns on the A/D.

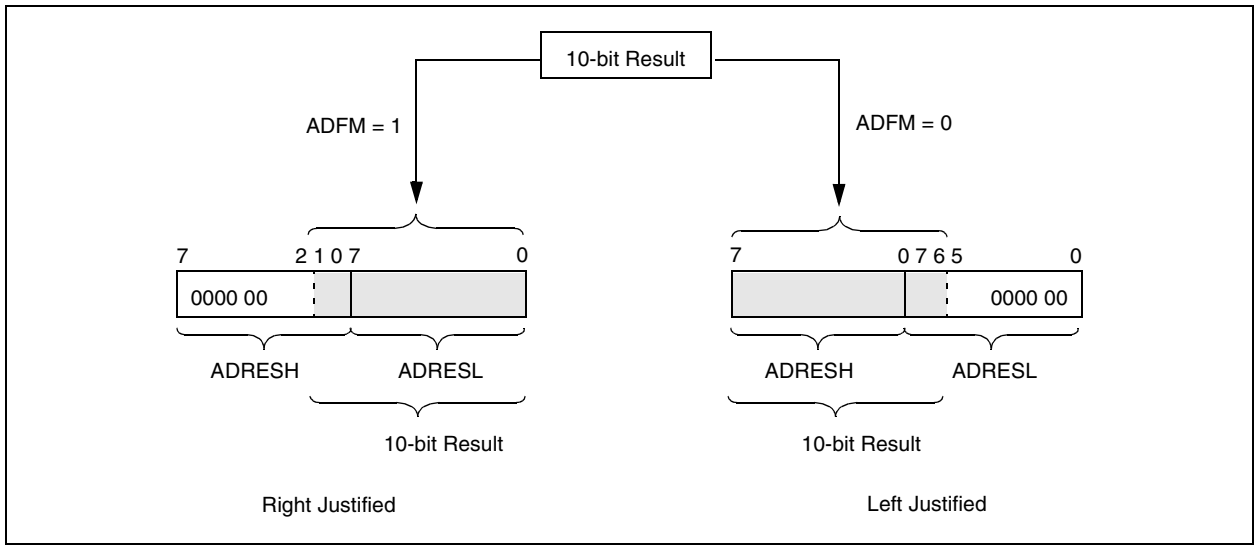
FIGURE 17-3: A/D CONVERSION TAD CYCLES



17.4.1 A/D RESULT REGISTERS

The ADRESH:ADRESL register pair is the location where the 10-bit A/D result is loaded at the completion of the A/D conversion. This register pair is 16-bits wide. The A/D module gives the flexibility to left or right justify the 10-bit result in the 16-bit result register. The A/D Format Select bit (ADFM) controls this justification. Figure 17-4 shows the operation of the A/D result justification. The extra bits are loaded with '0's. When an A/D result will not overwrite these locations (A/D disable), these registers may be used as two general purpose 8-bit registers.

FIGURE 17-4: A/D RESULT JUSTIFICATION



COMF **Complement f**

Syntax: [*label*] COMF f [,d [,a]

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

Operation: $(\bar{f}) \rightarrow$ dest

Status Affected: N, Z

Encoding:

0001	11da	ffff	ffff

Description: The contents of register 'f' are complemented. If 'd' is 0, the result is stored in W. If 'd' is 1, the result is stored back in register 'f' (default). If 'a' is 0, the Access Bank will be selected, overriding the BSR value. If 'a' = 1, then the bank will be selected as per the BSR value (default).

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example: `COMF REG, 0, 0`

Before Instruction
REG = 0x13
After Instruction
REG = 0x13
W = 0xEC

CPFSEQ **Compare f with W, skip if f = W**

Syntax: [*label*] CPFSEQ f [,a]

Operands: $0 \le f \le 255$
$a \in [0,1]$

Operation: (f) – (W),
skip if (f) = (W)
(unsigned comparison)

Status Affected: None

Encoding:

0110	001a	ffff	ffff

Description: Compares the contents of data memory location 'f' to the contents of W by performing an unsigned subtraction.
If 'f' = W**,** then the fetched instruction is discarded and a `NOP` is executed instead, making this a two-cycle instruction. If 'a' is 0, the Access Bank will be selected, overriding the BSR value. If 'a' = 1, then the bank will be selected as per the BSR value (default).

Words: 1

Cycles: 1(2)
Note: 3 cycles if skip and followed by a 2-word instruction.

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	No operation

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

If skip and followed by 2-word instruction:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation
No operation	No operation	No operation	No operation

Example:
```
HERE    CPFSEQ REG, 0
NEQUAL  :
EQUAL   :
```

Before Instruction
PC Address = HERE
W = ?
REG = ?
After Instruction
If REG = W;
PC = Address (EQUAL)
If REG ≠ W;
PC = Address (NEQUAL)

LFSR **Load FSR**

Syntax: [*label*] LFSR f,k

Operands: $0 \le f \le 2$
$0 \le k \le 4095$

Operation: $k \rightarrow FSRf$

Status Affected: None

Encoding:

1110 1111	1110 0000	00ff $k_7$kkk	k_{11}kkk kkkk

Description: The 12-bit literal 'k' is loaded into the file select register pointed to by 'f'.

Words: 2

Cycles: 2

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k' MSB	Process Data	Write literal 'k' MSB to FSRfH
Decode	Read literal 'k' LSB	Process Data	Write literal 'k' to FSRfL

Example: `LFSR 2, 0x3AB`

After Instruction
FSR2H = 0x03
FSR2L = 0xAB

MOVF **Move f**

Syntax: [*label*] MOVF f [,d [,a]

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

Operation: $f \rightarrow dest$

Status Affected: N, Z

Encoding:

0101	00da	ffff	ffff

Description: The contents of register 'f' are moved to a destination dependent upon the status of 'd'. If 'd' is 0, the result is placed in W. If 'd' is 1, the result is placed back in register 'f' (default). Location 'f' can be anywhere in the 256 byte bank. If 'a' is 0, the Access Bank will be selected, overriding the BSR value. If 'a' = 1, then the bank will be selected as per the BSR value (default).

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write W

Example: `MOVF REG, 0, 0`

Before Instruction
REG = 0x22
W = 0xFF

After Instruction
REG = 0x22
W = 0x22

22.1 DC Characteristics: PIC18FXX2 (Industrial, Extended) PIC18LFXX2 (Industrial)

PIC18LFXX2 (Industrial)			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial				
PIC18FXX2 (Industrial, Extended)			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
	VDD	**Supply Voltage**					
D001		PIC18LFXX2	2.0	—	5.5	V	HS, XT, RC and LP Osc mode
D001		PIC18FXX2	4.2	—	5.5	V	
D002	VDR	**RAM Data Retention Voltage(1)**	1.5	—	—	V	
D003	VPOR	**VDD Start Voltage** to ensure internal Power-on Reset signal	—	—	0.7	V	See Section 3.1 (Power-on Reset) for details
D004	SVDD	**VDD Rise Rate** to ensure internal Power-on Reset signal	0.05	—	—	V/ms	See Section 3.1 (Power-on Reset) for details
	VBOR	**Brown-out Reset Voltage**					
D005		PIC18LFXX2					
		BORV1:BORV0 = 11	1.98	—	2.14	V	85°C ≥ T ≥ 25°C
		BORV1:BORV0 = 10	2.67	—	2.89	V	
		BORV1:BORV0 = 01	4.16	—	4.5	V	
		BORV1:BORV0 = 00	4.45	—	4.83	V	
D005		PIC18FXX2					
		BORV1:BORV0 = 1x	N.A.	—	N.A.	V	Not in operating voltage range of device
		BORV1:BORV0 = 01	4.16	—	4.5	V	
		BORV1:BORV0 = 00	4.45	—	4.83	V	

Legend: Shading of rows is to assist in readability of the table.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode, or during a device RESET, without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption.
The test conditions for all IDD measurements in active Operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD
MCLR = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS, and all features that add delta current disabled (such as WDT, Timer1 Oscillator, BOR,...).

4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula Ir = VDD/2REXT (mA) with REXT in kOhm.

5: The LVD and BOR modules share a large portion of circuitry. The ΔIBOR and ΔILVD currents are not additive. Once one of these modules is enabled, the other may also be enabled without further penalty.

FIGURE 23-21: TYPICAL, MINIMUM AND MAXIMUM V_{OH} vs. I_{OH} (V_{DD} = 5V, -40°C TO +125°C)

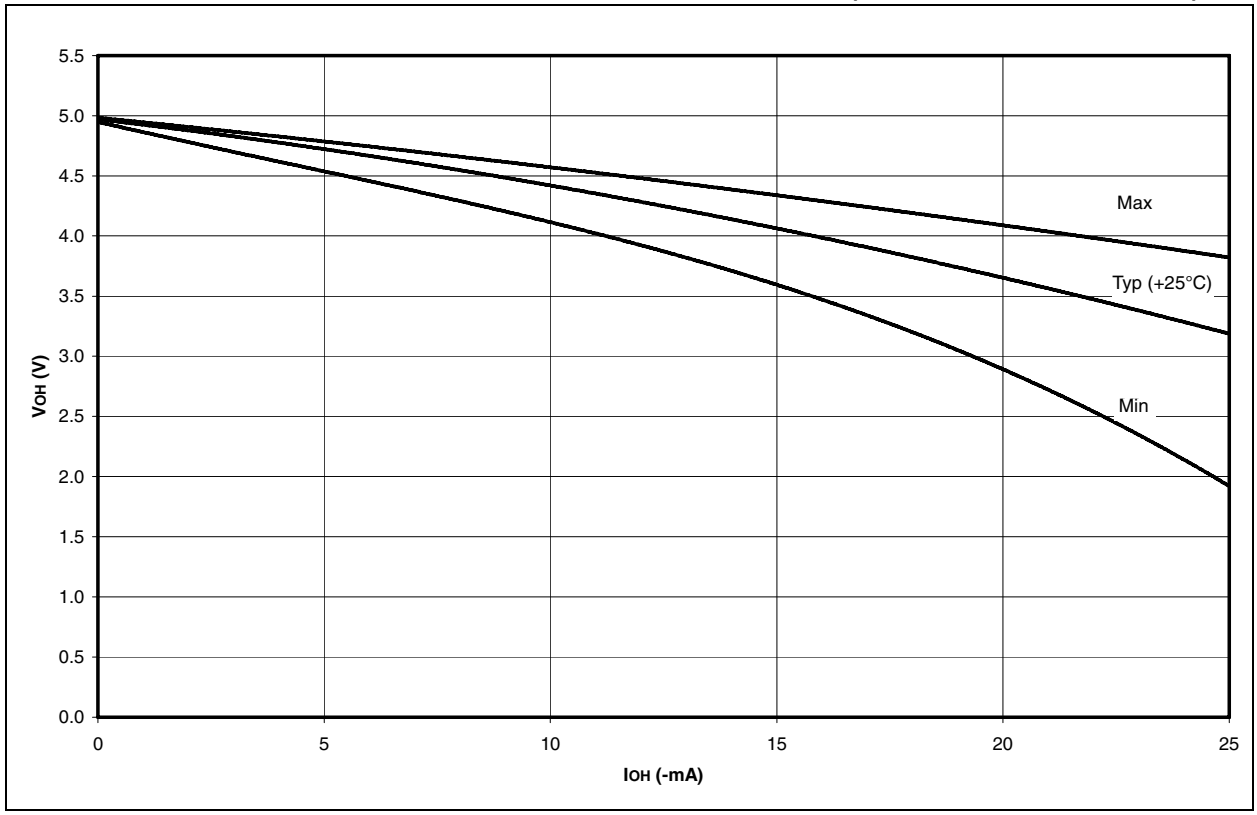
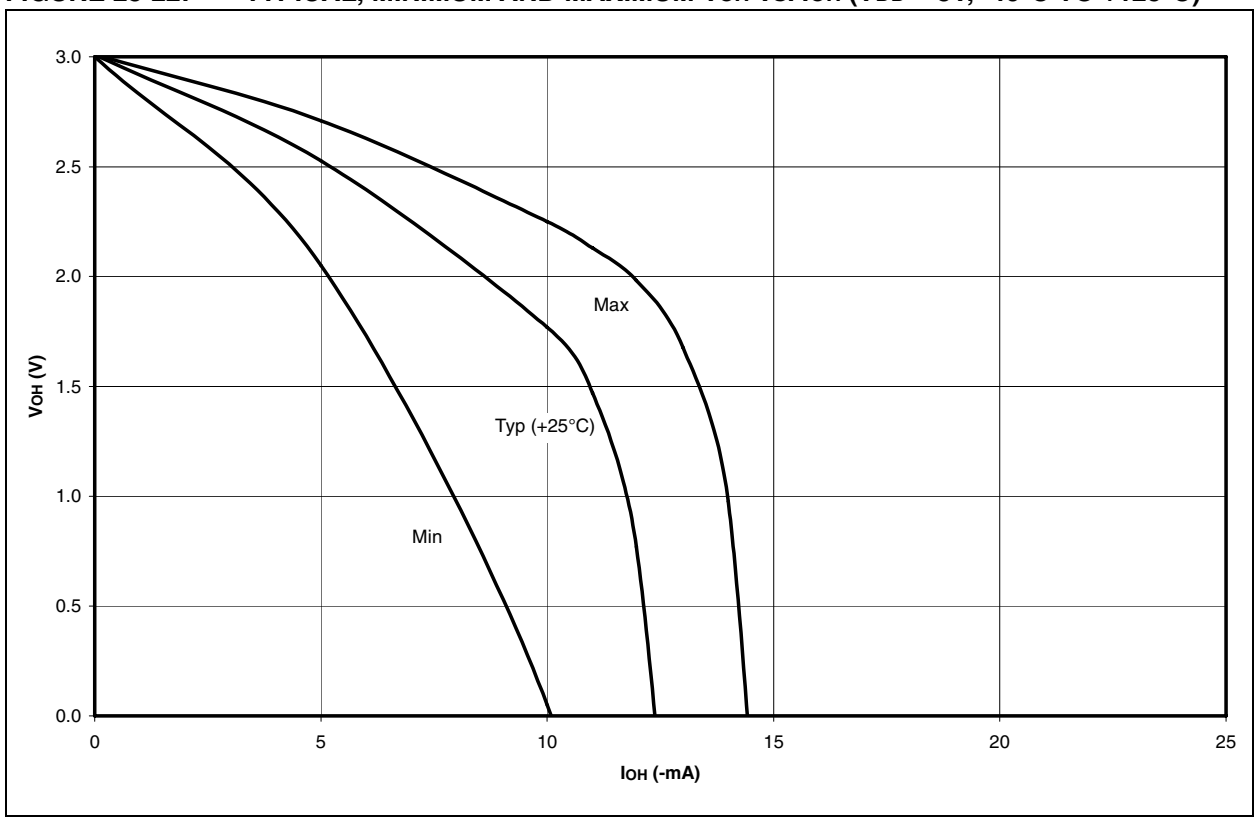
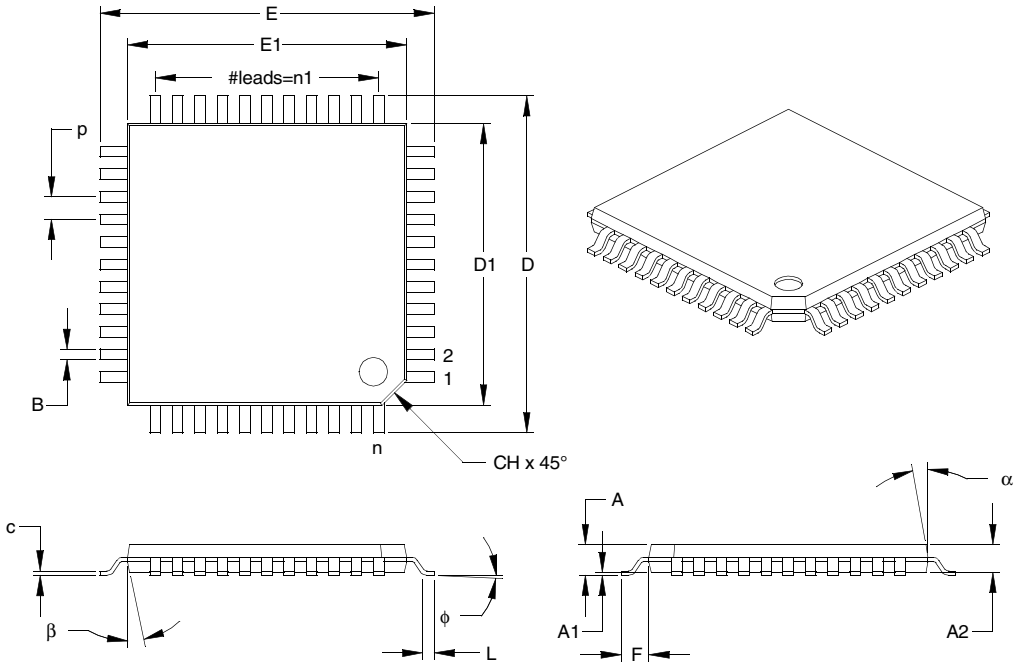


FIGURE 23-22: TYPICAL, MINIMUM AND MAXIMUM V_{OH} vs. I_{OH} (V_{DD} = 3V, -40°C TO +125°C)



44-Lead Plastic Thin Quad Flatpack (PT) 10x10x1 mm Body, 1.0/0.10 mm Lead Form (TQFP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES			MILLIMETERS*		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		44			44	
Pitch	p		.031			0.80	
Pins per Side	n1		11			11	
Overall Height	A	.039	.043	.047	1.00	1.10	1.20
Molded Package Thickness	A2	.037	.039	.041	0.95	1.00	1.05
Standoff	A1	.002	.004	.006	0.05	0.10	0.15
Foot Length	L	.018	.024	.030	0.45	0.60	0.75
Footprint (Reference)	F		.039 REF.			1.00 REF.	
Foot Angle	φ	0	3.5	7	0	3.5	7
Overall Width	E	.463	.472	.482	11.75	12.00	12.25
Overall Length	D	.463	.472	.482	11.75	12.00	12.25
Molded Package Width	E1	.390	.394	.398	9.90	10.00	10.10
Molded Package Length	D1	.390	.394	.398	9.90	10.00	10.10
Lead Thickness	c	.004	.006	.008	0.09	0.15	0.20
Lead Width	B	.012	.015	.017	0.30	0.38	0.44
Pin 1 Corner Chamfer	CH	.025	.035	.045	0.64	0.89	1.14
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

* Controlling Parameter

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

REF: Reference Dimension, usually without tolerance, for information purposes only.

See ASME Y14.5M

JEDEC Equivalent: MS-026

Drawing No. C04-076

Revised 07-22-05

APPENDIX E: MIGRATION FROM MID-RANGE TO ENHANCED DEVICES

A detailed discussion of the differences between the mid-range MCU devices (i.e., PIC16CXXX) and the enhanced devices (i.e., PIC18FXXX) is provided in AN716, “Migrating Designs from PIC16C74A/74B to PIC18F442”. The changes discussed, while device specific, are generally applicable to all mid-range to enhanced device migrations.

This Application Note is available as Literature Number DS00716.

APPENDIX F: MIGRATION FROM HIGH-END TO ENHANCED DEVICES

A detailed discussion of the migration pathway and differences between the high-end MCU devices (i.e., PIC17CXXX) and the enhanced devices (i.e., PIC18FXXX) is provided in AN726, “PIC17CXXX to PIC18FXXX Migration”. This Application Note is available as Literature Number DS00726.

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A

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PIC18FXX2 PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	–	X	/XX	XXX
Device		Temperature Range	Package	Pattern

Device	PIC18FXX2(1), PIC18FXX2T(2); VDD range 4.2V to 5.5V PIC18LFXX2(1), PIC18LFXX2T(2); VDD range 2.5V to 5.5V
Temperature Range	I = -40°C to +85°C (Industrial) E = -40°C to +125°C (Extended)
Package	PT = TQFP (Thin Quad Flatpack) SO = SOIC SP = Skinny Plastic DIP P = PDIP L = PLCC
Pattern	QTP, SQTP, Code or Special Requirements (blank otherwise)

Examples:

a) PIC18LF452 - I/P 301 = Industrial temp., PDIP package, Extended VDD limits, QTP pattern #301.

b) PIC18LF242 - I/SO = Industrial temp., SOIC package, Extended VDD limits.

c) PIC18F442 - E/P = Extended temp., PDIP package, normal VDD limits.

Note 1: F = Standard Voltage range
LF = Wide Voltage Range

2: T = in tape and reel - SOIC, PLCC, and TQFP packages only.